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Acquisitions

ITI TranscenData Acquires Proficiency

1 July 2009

International TechneGroup Incorporated (ITI) announced that the ITI TranscenData business has acquired Proficiency. “Proficiency is a strategic acquisition that extends our interoperability capabilities and strengthens ITI’s overall focus of product development productivity”, said ITI Chairman and CEO, Mike Lemon.

“This is an exciting milestone for our company,” said ITI TranscenData President, Don Hemmelgarn. “We now provide the most comprehensive suite of solutions in the Product Data Interoperability industry. This alignment is not only beneficial for existing ITI and Proficiency clients, but for companies still weighing and planning interoperability solutions. We are now the ideal partner, offering the highest quality CAD model data to manufacturing enterprises and their supply chain.”

[ITI](#) is a global company helping clients achieve world class product development productivity. ITI TranscenData provides interoperability solutions that enable companies to effectively exchange, reuse, integrate and share engineering product data among diverse software applications. ITI TranscenData solutions are aimed directly at reducing and eliminating non-value-added time and costs associated with reusing product data. ITI TranscenData offers PLM Integration services, PLM and CAD Data Migration solutions and software products such as CADfix®, CADIQ® and DEXcenter™.

Proficiency’s Collaboration Gateway™ technology will continue to be offered through the ITI TranscenData business, providing the automated re-mastering of parametric CAD data from one CAD system into another, including all of the 3D design intelligence, such as features, sketches, parameters and constraints, manufacturing info, metadata and assembly information. Proficiency supports interoperability between: Pro/Engineer, I-deas, UG-NX, Catia V4 and Catia V5. Alex Tsechansky, Vice President of Research and Development for Proficiency commented, “Over the past 10 years Proficiency has developed product knowledge migration capabilities between all high end CAD platforms. Combining this technology with ITI TranscenData’s solutions will be a win-win for both the business

and our customers.”

The acquisition of Proficiency by ITI TranscenData will offer strength and stability to the existing client bases of both companies. When news of the acquisition was shared with existing ITI TranscenData and Proficiency clients, it was well received. “ITI TranscenData looks forward to working with the Proficiency team to ensure a rapid and seamless transition”, said Don Hemmelgarn. “Our combination will create excellent growth opportunities for our customers and employees.”

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CIMdata News

CIMdata, Inc. Successfully Introduces PLM Certificate Program

30 June 2009

CIMdata, Inc., the leading global PLM consulting and research firm announces the successful start of its new PLM Certificate Program with recent sessions held in Helsinki, Finland and Ann Arbor, Michigan, USA. CIMdata’s [PLM Certificate Program](#) is the flagship offering of *CIMdata PLM Leadership*—the PLM industry’s most comprehensive non-biased education and training offering for today’s PLM professionals.

CIMdata’s PLM Certification Program prepares industrial professionals at several levels to successfully address the challenges inherent in PLM implementations. According to Tanmay Aggarwal of IDS Infotech Ltd., “The PLM Certificate Program provided me with a very thorough understanding of this critical business strategy.” Commenting on the response CIMdata has received since the program’s introduction in April, Mr. Peter Bilello, CIMdata Vice President and PLM Certificate Program Coordinator, said that the global response has been extremely positive. Mr. Bilello noted, “Since the program’s introduction in late April, we have received inquiries and registrations from four continents. This is a very positive sign and it clearly indicates that companies throughout much of the world view PLM as a strategic business approach that must be understood and pursued no matter the economic climate.” He added that these responses validate CIMdata’s experience that the PLM industry throughout the world clearly needs a best-practice-based education and training program to provide the solid foundation necessary to successfully define, implement, and continuously improve today’s and tomorrow’s PLM environments. “It is for this reason that CIMdata will continue to expand the CIMdata PLM Certificate Program and will offer it beyond the North American and European markets in upcoming months and years.” said Mr. Bilello.

This five-day assessment-based program includes an intimate classroom experience, individual and team-based exercises, and individual evaluations of achievement. Additionally, the program provides candidates with intensive and extensive exposure to a team of CIMdata’s experts. Upon completion of the program, each participant receives a CIMdata PLM Certificate and thereby becomes a member of CIMdata’s global *PLM Leadership* community. The CIMdata PLM Certification Program is built on CIMdata’s more than 25 years of extensive world-wide experience guiding industrial companies in successfully defining and implementing best-in-class PLM strategies and tactics.

The next CIMdata PLM Certificate Program is scheduled for late September, 2009 in Andover, MA outside of Boston. Please refer to [PLM Certificate Program](#) for full details of this exclusive education program.

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About CIMdata

CIMdata, a leading independent worldwide firm, provides strategic consulting to maximize an enterprise's ability to design and deliver innovative products and services through the application of Product Lifecycle Management (PLM) solutions. Since its founding more than 25 years ago, CIMdata has delivered world-class knowledge, expertise, and best-practice methods on PLM solutions. These solutions incorporate both business processes and a wide-ranging set of PLM enabling technologies.

CIMdata works with both industrial organizations and suppliers of technologies and services seeking competitive advantage in the global economy. In addition to consulting, CIMdata conducts research, provides PLM-focused subscription services, and produces several commercial publications. The company also provides industry education through PLM certificate programs, seminars, and conferences worldwide. CIMdata serves clients around the world from offices in North America, Europe, and Asia Pacific.

To learn more about CIMdata's services, visit our website at www.CIMdata.com or contact CIMdata at: 3909 Research Park Drive, Ann Arbor, MI 48108, USA. Tel: +1 (734) 668-9922. Fax: +1 (734) 668-1957; or at Siriusdreef 17-27, 2132 WT Hoofddorp, The Netherlands. Tel: +31 (0)23 568-9385. Fax: +31 (0)23 568-9111.

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Last Opportunity to Vote in our Current Opinion Poll

CIMdata would like your input on how the current economic situation is affecting the progress of your PLM program. Results will be announced next Friday so [vote](#) now to have your feedback included.

The results of these polls are tabulated as you vote. The results are completely anonymous. If you are currently logged in your vote will not be connected to your personal information in any way

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Company News

Assemblies Over 20 000 Parts – Easy With KOMPAS-3D; ASCON Awards Winners of 7th KOMPAS-3D Modelling Contest

2 July 2009

ASCON Group announced the results of the KOMPAS-3D Modelling Contest 2009. This year the Contest again established a new record — 81 projects from 54 industrial enterprises, designed with the 3D Parametric Modelling Solution, KOMPAS-3D.

A range of projects from different industry branches were submitted for the contest, including machinery, automotive, oil, gas, shipbuilding, aerospace and defense, architecture, electronics and many others. Due to the growing popularity of ASCON' solutions in industrial and civil engineering, organizers assigned two nominations for the competition: one for mechanical engineering and the second for industrial and civil engineering.

Most of event participants are longstanding clients of KOMPAS-3D. Quite a number of industrial enterprises have just recently started to work with the system but they already obtained impressive results. Among them are Oscar Nurtaev from PERMATECH Inc., USA, and Michał Prech, Poland, who

CIMdata PLM Industry Summary

were awarded special prizes. Many projects at KOMPAS-3D Modelling Contest 2009 exceed 10 000 parts in the assembly and even more. Here are the winners of the contest:

Mechanical Engineering

1st Place

Project:

Autolift with working platform PSS-01 31017 E

Developer:

OOO «Pozharnye Sistemy», Tver

Total parts:

2453

Industrial and Civil Engineering

1st Place

Project:

The line of sheet glass production

Developer:

OAO «Saratovstrojsteklo», Saratov

Total parts:

20814

At <http://ascon.net/showcase/gallery/> you will find all the winners and participants of KOMPAS-3D Modelling Contest 2009, as well as projects' gallery of previous years. In the near future ASCON will start to accept new applications and you are welcome to participate in the Contest 2010.

Special Offer from ASCON:

- CAD for RENT – rent KOMPAS-3D at 650 euro per Year
- CAD TRADE IN – exchange your outdated CAD to KOMPAS-3D with 50% discount

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COADE CADWorx P&ID Featured in Chemical & Engineering Progress May 2009 Issue

1 July 2009

COADE announced that the May 2009 issue of Chemical & Engineering Progress magazine featured an article on CADWorx P&ID, a primer on flow diagrams that describes the distinctions between a basic block flow diagram and the process flow diagram (PFD) which is the precursor of the P&ID, an acronym for process and instrumentation diagram and piping and instrumentation diagram, a useful tool that, with the modern technology provided by CADWorx P&ID, has become even more valuable and vital to the plant designer and engineer.

The article describes how, with CADWorx P&ID, these are no longer passive drawings that hold information that only skilled CAD operators can access but intelligent tools that play a valuable and vital

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role in the design process. This value is in part because P&IDs are the best way to accurately document the operation of the process and also because they are a health and safety document required under government regulations.

Information on COADE and its products can be found at <http://www.coade.com>. A copy of the article can be found at <http://coade.typepad.com/coadeinsider/2009/06/cep-article-piping-and-instrument-diagrams.html>.

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COADE Donates CADWorx Plant and CADWorx P&ID Software to Louisiana Technical College

30 June 2009

COADE announced that the company has donated 43 seats of CADWorx Plant and 43 seats of CADWorx P&ID to Louisiana Technical College (LTC), Region 8, Delta Ouachita Campus, in West Monroe, Louisiana, to train students on using software for plant design and process and instrumentation diagram applications. The software will be used by students in the Drafting & Design Technology program, with courses that focus on piping, architectural, civil, mechanical, structural and electrical drafting and design. LTC Region 8 includes 8 sites, the oldest of which was established in 1950.

“The CADWorx software series uses the latest technology and fulfills the industries’ needs, allowing our students to train on the latest technologies, thereby increasing their value to employers and their opportunities for employment,” explained Sue Lee, Drafting and Design Technology Professor at LTC. “CADWorx P&ID provides the flexibility to create process diagrams with varying levels of information and with the minimum of effort, while CADWorx Plant provides them the flexibility of drawing in orthographic or 2D, or 3D, and includes the Alias ISOGEN program, the fastest way to create Isometric drawings,” Lee added.

Information on the college can be found at www.region8.ltc.edu. Information on COADE and its products is at www.coade.com.

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Delcam Adds to Toronto Support

1 July 2009

Delcam’s Canadian subsidiary, Delcam Canada, headquartered in Windsor, Ontario, has added Chris Crane as an additional Applications Engineer for the Greater Toronto Area. Mr. Crane has worked in a number of manufacturing facilities in the region for almost ten years. He has gained extensive experience with a variety of CNC machines and manufacturing processes, both while working as a tool and die programmer and while at leading machine tool distributors, Mazak Corporation Canada and EMEC Machine Tools.

Commenting on Mr. Crane’s appointment Delcam VP for Canada Mark Cadogan said, “Chris’s machining background is going to be a valuable asset for all our Toronto-based customers looking for training and support from Delcam.” The appointment comes during a busy year for the Canadian subsidiary, despite the downturn in the automotive industry in the area, on which the manufacturing sector is so heavily dependent.

New sales are being achieved across the complete range of Delcam software. However, the PowerMILL

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CAM system continued to contribute the largest proportion of the revenue, due mainly to the growing demand for more powerful five-axis machining software from Canadian manufacturing companies. Like its parent company, Delcam Canada is also diversifying outside of its traditional markets in the toolmaking industry to companies looking for particular solutions in production machining, especially in the aerospace and medical industries.

Mr. Cadogan was quick to praise the contribution of his whole team to the continued strong performance. “Over the past year, we have concentrated on getting back to basics,” he commented. “The re-structuring happening for many businesses in the Windsor area has kept our support team very busy. Mr. Crane’s appointment is a clear demonstration of our strong commitment and willingness to work with our customers in the Toronto area.”

For further information on Delcam’s CAD/CAM software in Canada, please contact: -

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Dyadem Expands Direct Presence in Europe

2 July 2009

Dyadem announced that it is expanding its presence in Europe in order to support its growing European customer base. Dyadem has seen its revenues grow 357% from 2003 to 2008, and now has offices in Paris and Amsterdam to complement its existing infrastructure in London, Houston and its headquarters in Toronto, Canada.

Dyadem's software helps companies of all sizes centralize and integrate their Operational and Quality Risk Management initiatives and comply with various industry regulations and standards. It provides a way for companies to better manage the quality of the products that carry their brand and reduce the risks associated with bringing those products to market.

Building its international sales team, Dyadem has hired Bruno Navarrete to lead its development in France and Southern Europe and Arie Kievit to lead business development in the Netherlands and Northern Europe. Kievit joins Dyadem from AspenTech where he held the role of Global Account Director and has also served as BENULUX Country Manager at i2 Technologies and Manugistics where he gained experience in the discrete manufacturing industry and with ERP software systems. Kievit holds an MBA and is fluent in Dutch, German and English.

Bruno Navarrete joins Dyadem from EPIC Data where he was the country manager for France. He conducted new business development towards industrial companies especially in Electronics and

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Military sectors. Previously, he worked at Formations Systems where he gained knowledge of product lifecycle management for the Consumer Product Goods industry. Navarrete has gained broad experience in both process and discrete industries while working for AspenTech, as Sales Director Southern Europe in Oil & Gas, and Baan, where he was responsible for a profit center in France for the Automotive industry vertical. He is fluent in French and English and holds degrees in science and math as well as an MBA.

Dyadem's Stature platform is built on the principles of continuous improvement, providing a single enterprise platform to identify, measure, mitigate and communicate risks to all stakeholders within an organization. This helps companies identify risk factors and improve Safety, Health and Environment (SHE) compliance and bring better quality products to market faster.

[Dyadem](#) helps organizations to accurately capture trends, implement preventive measures, efficiently execute processes, and make informed decisions based on project and business process performance, all in real-time. Stature is a Web-based software solution that allow users throughout the world to securely work and collaborate as a single virtual team.

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Enthusiastic and Positive Global Adoption of MapleSim Beats Expectations

25 June 2009

Maplesoft™ announced that its recently released modeling and simulation software, MapleSim™, has received tremendous response from around the world. Close to 500 licenses have been sold in the six months since its release in December 2008.

“MapleSim saved me many hours of work because the model maps onto the topology of the physical system and the dynamic equations do not have to be developed by hand,” said Dr. Richard Gran, president and CEO of The Mathematical Analysis Company, and an early user of MapleSim.

“MapleSim converts a painstaking and laborious process into one that is simple and enjoyable.” Dr. Gran used MapleSim to rapidly develop a model of an eight-room house to investigate a new home heating system controller.

Unlike traditional tools, MapleSim uses physical modeling techniques to create model diagrams that map directly to the physical systems. This new tool gives the industry significant savings in time and cost, because its symbolic techniques create highly efficient models faster and with less effort.

MapleSim has received several accolades from engineers, researchers, instructors, and the media. In a review of the product for IEEE Spectrum magazine, software reviewer Ken Foster writes, “MapleSim has a lot in common with MathWorks’ Simulink, but, interestingly, it works by finding the differential equations for a system, which Maple simplifies analytically before solving. This process is potentially faster and more accurate than Simulink’s purely numerical approach.” (“New Math”, IEEE Spectrum, vol. 46, no. 4 (April 2009), <http://www.spectrum.ieee.org/computing/software/new-math>)

“MapleSim is beginning to bring about a shift in modeling and simulation practices,” said Jim Cooper, president and CEO of Maplesoft. “Engineers, researchers, and instructors have excitedly told us they see MapleSim as a valuable tool in dramatically shortening product development cycles and gaining more insights to research and teaching. With its revolutionary approach and computationally superior techniques, MapleSim will continue to demonstrate the impact this one product can have on industry.”

Pricing and Availability

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Single-user professional licenses of MapleSim are available for US \$2,995. Volume, upgrade, and academic discounts apply. It is available directly from the Maplesoft Web Store or by contacting Maplesoft Sales at 1-800-267-6583. Outside of the US and Canada, the products are available from a local Maplesoft reseller.

Visit <http://www.maplesoft.com> to learn more.

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NSERC-Toyota-Maplesoft Industrial Research Chair in Mathematics-Based Modeling and Design Announced

29 June 2009

Maplesoft announced a partnership with the University of Waterloo, Natural Sciences and Engineering Research Council (NSERC) and Toyota Corporation, that will produce new methods for modeling physical systems. The Industrial Research Chair is being granted to Dr. John McPhee, from the Department of Systems Design Engineering at the University of Waterloo, and Executive Director of the Waterloo Centre for Automotive Research (WatCAR).

Current engineering practices create computer models that are numerical in nature, to explore different design concepts and evaluate their performance. A more natural way to model a system is to use mathematics, and the main goal of this research is to develop the theory and computer algorithms necessary to automatically create engineering models in a mathematical form. This will speed up the model-based development approach for new products, an approach that is being pioneered by Maplesoft, and embraced by the automotive industry as it strives to become more efficient and responsive to consumer demands.

Dr. John McPhee and his team will collaborate with experts at Maplesoft and Toyota to develop these math-based models and computer simulations, with a focus on automotive applications such as vehicle dynamics, powertrains, and hybrid electric vehicles. With symbolic computation at its core, Maplesoft was among the first companies to realize the impact that mathematics-based modeling will have on vehicular research. With the newly released MapleSim aiding multi-domain modeling, it will play a crucial role in the research which aims to enhance the development of multi-domain system models comprising mechanical, electrical, hydraulic, and other components.

“There is currently a crisis in our automotive sector,” said Dr. John McPhee. “To be globally competitive, automotive manufacturers must design new products faster, safer, and better. The proposed research will speed up the automotive design process, and result in fewer costly prototypes and experimental testing.”

Maplesoft and Dr. John McPhee have a long standing collaboration. In addition to several contracts, as Executive Director of the Waterloo Centre for Automotive Research, Dr. McPhee has supported or participated in several major funding programs. Through these various multi-million dollar initiatives, he has access to a world-class team of researchers with expertise in a wide range of automotive-related fields.

“This research proposal is central to Maplesoft’s philosophy of technology development,” said Jim Cooper, President and CEO of Maplesoft. “Access to new algorithms for mathematics-based modeling will be crucial and will have a lasting impact when incorporated into current and future commercial products developed by our company. Maplesoft is confident that the results of this new research will

CIMdata PLM Industry Summary

prove beneficial for the company and the sector on a larger scale.”

Maplesoft’s partnership will provide direct and early access to research results which can be incorporated into the product development cycles at Maplesoft.

Visit <http://www.maplesoft.com> to learn more.

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Rand Worldwide Now Offering Siemens PLM Software to Meet Customer Driven Demands

29 June 2009

Siemens PLM Software announced that [Rand Worldwide](#), a global leader in providing technology solutions to organizations with engineering design and information technology requirements, is now a Siemens PLM Software Solutions Partner.

“The cornerstone of the relationship is based on providing the market place with PLM software and professional services that exceed customer expectations and drive business value. In order to provide the world class solutions and support our customers have come to expect to a wider audience, we look towards Solutions Partners who consistently exceed customer expectations. Rand Worldwide shares the same philosophy and values, as we do, strong support to help customers turn more ideas into successful products,” said Kerry Grimes, vice president, global solution partner sales, Siemens PLM Software.

Rand Worldwide will offer Siemens PLM Software’s solutions to provide collaborative product data management that allows customers to work together and innovate more intelligently by connecting people and processes with knowledge.

“Rand Worldwide has a proven track record helping clients select and implement advanced technologies that allow them to turn product ideas into reality. [Siemens PLM Software](#) solutions provide the depth and breadth needed to support continuous innovation. The synergy of the partnership between Rand Worldwide and the Siemens PLM Software offers clients an ideal platform for delivering efficiency, productivity and flexibility to all aspects of the product lifecycle,” said Joseph Oswald, executive vice president, PLM Operations - North America and Europe, Rand Worldwide.

Siemens PLM Software increases the success and productivity of channel partners through multiple enablement programs which include close channel management support, sales and technical training as well as marketing initiatives. According to its most recent annual channel partner survey, partners gave Siemens PLM Software top ratings in the following categories: product understanding, sales call support, Partner Portal and sales training delivery.

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Seoul Data System Introduces ROHR2 Program System in Korea

19 June 2009

SEOUL DATA SYSTEM Ltd, Seoul, announced the business partner of SIGMA GmbH, Germany for the sales and support of the CAE products ROHR2 and SINETZ in Korea.

SEOUL DATA SYSTEM is well known as a specialist engineering & technology services company, focused on enhancing their client's product / project engineering efficiency and providing services for CAD / CAM / CAE products.

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The cooperation with SIGMA and SEOUL DATA SYSTEM chairman Mr. Youn is basing on the long experience in distributing engineering software in Korea.

Along with his experiences in the Korean market he is the perfect partner for SIGMA in this area.

About: ROHR2 and SINETZ

ROHR2 is one of the leading Pipe Stress Analysis tools, standard software for static and dynamic analysis of piping systems and structural frameworks.

The software is equipped by a range of additional features enhancing the engineer's daily job, as there are FEM analysis, isometric capabilities and a wide range of interfaces covering the leading CAD/CAE systems.

ROHR2 is developed continuously in order to incorporate the ongoing changes in the stress calculation codes and norms but also to improve the user interface and extend the capabilities of ROHR2 according to the user's needs.

SINETZ is the design solution for Steady State Calculation of Flow Distribution, Pressure Drop and Heat Loss in Branched and Intermeshed Piping Networks for compressible and incompressible media.

About: SIGMA

SIGMA, established in 1989 in Dortmund, Germany has emerged as a partner of choice for leading international companies with its software and the wide variety engineering services. SIGMA is known as one of the leading engineering specialists in the Pipe Stress Business in Europe, offering field tested products, strongly adapted to the users needs.

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Virage Logic Expands Presence in India to Serve Growing Market Demand for Broad IP Portfolio

30 July 2009

CIMdata PLM Industry Summary

[Virage Logic Corporation](#) announced it has expanded its presence in India with the appointment of CoreEL as its sales representative. CoreEL joins a growing global network of sales representatives that complement and expand the reach of Virage Logic's direct sales channel. CoreEL's more than 15 years experience working with India's networking, telecom, computing, consumer, industrial, defense and automotive customers make them ideally suited to represent Virage Logic's broad portfolio of silicon proven IP.

"As the semiconductor industry continues to globalize and more semiconductor companies rely on their India-based teams to make SoC design project decisions, the time was right to bring CoreEL on board to service our growing India customer base," noted Jai Iyer, Virage Logic's vice president of Asia sales. "We are confident that the combination of CoreEL's strong technology and design services experience will enable them to provide the superior sales and support services Virage Logic's customers worldwide have come to expect."

"India is rich in engineering talent and a target for companies worldwide to tap into the engineering resources," said Vishwanath Padur, vice president of Sales and Marketing for CoreEL. "With Virage Logic's highly differentiated IP offering - including embedded SRAMs, embedded NVMs, embedded memory test and repair, logic libraries, memory development software, and interface IP solutions - we look forward to being able to provide even greater value to our extensive customer base as we help them address their SoC design challenges."

About CoreEL

CoreEL Technologies, headquartered in Bangalore, India, is a Technology company with businesses spread across Third-party technology Solutions, VLSI & Embedded training and Value added Design Services. Its Technology Solutions business covers EDA, Semiconductors and Security & Surveillance product segments. CoreEL provides Sales, Application Support and Training for all the products that it represents. Besides, CoreEL offers Turn Key Design Solutions for customers in market segments like the Defense & Aerospace, Telecom & Networking, Industrial and Digital Video & Signal Processing. Its expertise includes FPGA Design, HW and SW development, High Speed PCB Design. For more information, visit <http://www.coreel.com>.

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Virginia Tech And The MathWorks Collaborate To Expand Matlab And Simulink Use Throughout Engineering Students And Faculty

30 June 2009

[The MathWorks](#) announced that it has joined with [Virginia Tech College of Engineering](#) in a three-year initiative to enable more competitive, cutting-edge, and collaborative education for the university's engineering and science students.

As part of this three-year relationship, The MathWorks will provide resources and support for the continued use and development of course components that utilize MathWorks tools. The MathWorks will also sponsor Virginia Tech's Joseph F. Ware, Jr. Advanced Engineering Laboratory (Ware Lab, <http://www.eng.vt.edu/warelab/>) with software for technical computing and Model-Based Design. The Ware Lab houses content for approximately 13 engineering-based design competitions, such as [EcoCAR](#): The NeXt Challenge, for undergraduate students. Access to [MATLAB](#) and [Simulink](#) in the Ware Lab will afford students the opportunity to gain expertise using industry-standard software tools in preparation for entering the workforce.

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“To stay competitive, universities are seeking new ways to meet increasing expectations from students that they receive the highest-level access to and training on their industry’s most relevant technology tools,” said Tom Gaudette, manager of education technical marketing at The MathWorks. “Virginia Tech’s recognition of its student body needs and expectations from the school curriculum established the framework upon which this relationship with the university is built.”

“Our expanded relationship with The MathWorks provides an extraordinary asset for our engineering and science students,” said Glenda Scales, associate dean, international programs and information technology, Virginia Tech College of Engineering. “We continuously strive to create more competitive programs and curriculum, and we know our students expect to learn about and gain expertise in cutting-edge tools that prepare them for industry. By offering MathWorks software, we achieve both of these goals.”

This three-year collaboration builds upon years of Virginia Tech students using MathWorks software in academic competitions, such as [EcoCAR](#) and [Challenge X](#). MathWorks software has also previously been licensed for use on laptops by Virginia Tech students; all undergraduate engineering students receive an engineering software bundle that includes 17 MathWorks products.

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Events News

Cadence CDNLive! EMEA User Conference Energizes the Electronics Industry

29 June 2009

Cadence Design Systems, Inc. celebrated the successful start of its series of worldwide CDNLive! user conferences. More than 480 delegates from 200+ companies attended the first conference, which took place in Munich, Germany, from May 18 to 20 before continuing on to Tokyo, Japan, July 16-17. The conference brought together Cadence® technology users and developers, along with industry experts, to investigate challenges and synthesize solutions. The central theme of this year’s events was to energize, inspire and educate members of the electronics industry to help them generate fresh ideas for tackling some of today’s most critical design challenges.

Attendees of this year’s EMEA event were welcomed by a keynote speech from Lip-Bu Tan, President and CEO of Cadence. Tan spoke about the ways in which semiconductor companies can succeed in the present economy, and that success lies within the development of new products that truly offer value. Technologies on the horizon (such as 4G, smart grid power, and medical electronics) and emerging markets offer an opportunity to re-energize the semiconductor industry.

In addition, guest speaker Ian Drew, Executive Vice President of Marketing at ARM, presented a keynote speech that discussed ARM’s business environment and strategy. He examined how current market trends such as “Internet everywhere” and “embedded growth” are driving innovation within the global semiconductor market, and how ARM-based architecture lies at the heart of many of these technological innovations.

“Our vision for CDNLive! EMEA this year was to focus on innovation, and to demonstrate how the use of advanced solutions, tools and methods in the design process can help our customers to launch successful products,” said Wolfgang Stronski, Marketing Director for EMEA at Cadence. “It is an exciting time to be part of the electronics industry, as the creativity of design engineers is assisting new

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technologies to help to define our lives. At this event, we wanted to help delegates learn new ways to overcome design complexities that will enable our customers to produce leading-edge products that can quickly respond to market and consumer requirements.”

This year at CDNLive! EMEA, [Cadence](#) hosted a special academic track designed for university representatives, and organized by Cadence Academic Network members with the aim to align and fuel the interactions between industry and academia. Universities from across Europe presented their latest design experiences based on Cadence solutions and design flows. Moreover, Cadence announced the winners of the second EDA contest for students in EMEA. Students from Portugal, France, Germany, Poland, Netherlands, Greece, Sweden and Austria had signed up to participate and demonstrate their skills learned on the Cadence Virtuoso® custom IC design platform. Américo Dias and Daniel Oliveira from the Microelectronics Students' Group of the Faculty of Engineering of the University of Porto, Portugal received the title ‘Fastest full custom layout designer of the year’ by Cadence and were awarded with free training from Cadence Education Services valued at € 1.400.

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COADE Webinar on Using PV Fabricator for Developing Vessel Fabrication Drawings Scheduled for July 16, 2009

30 June 2009

COADE announced that a webinar is scheduled for July 16 at 12 noon CDT on “Developing Vessel Fabrications Drawings using PV Fabricator.” Participants will learn how to improve the speed, accuracy and consistency of their pressure vessel fabrication deliverables and how COADE PV Elite analysis information can be used by COADE PV Fabricator to accurately populate drawings, details, nozzle schedules, drawings boarders, bills of material and other fabrication deliverables. This COADE Webinar Series event, produced by the PV Elite development team, will feature Chris Schiller, Technical Sales Representative - Plant Engineering Solutions at COADE.

A webinar registration form is at <https://www1.gotomeeting.com/register/404541361>, and information on the webinar is at <http://coade.typepad.com/cadworx/2009/06/webinar-july-16th-1200pm-cst-developing-vessel-fabrication-drawings-using-pv-fabricator.html> Information on COADE and its products can be found at <http://www.coade.com>.

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Delcam to Show Complete CAM Range in Vietnam

1 July 2009

Delcam will demonstrate its complete family of CAM software at the MTA Vietnam exhibition to be held in Ho Chi Minh City from 8th to 11th July. The complete range comprises PowerMILL for high-speed and five-axis machining, FeatureCAM for feature-based programming, PartMaker for Swiss-type lathes and turn-mill equipment, and ArtCAM for engraving and routing. Together, these programs comprise the world’s most comprehensive range of CAM software from a single supplier. This broad coverage is one of the reasons why Delcam was again ranked as the world’s leading specialist supplier of NC software and services in the recent report by US analysts CIMdata.

The new release of PowerMILL offers the fastest-ever toolpath generation on multi-processor computers, giving greatly increased user productivity. The new release incorporates the latest

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background-processing and multi-threading technologies and so uses the full power of recent hardware developments to reduce calculation times and increase output dramatically. Other enhancements to further increase productivity include reduced memory usage when programming the largest and most complex parts, and improved ordering to give faster cycle times on the machine tool.

FeatureCAM 2009 incorporates enhancements across its complete range of functionality. An important focus has been increased options for more complex machines, such as mill-turn equipment, and four- and five-axis mills. This will allow users to tackle more sophisticated parts than could be programmed before. Developments have also continued increase the efficiency of the more fundamental machining operations, including turning and three-axis milling.

Major highlights of the new release of PartMaker include a revamped and more productive user-interface, improved capabilities for programming directly on solid models and more realistic machine simulation for the increasingly-complex machine architectures of today's multi-axis turn-mill centres and Swiss-type lathes. The enhanced user interface will make PartMaker users even more productive in programming their CNC equipment, while offering new users an even easier to learn, more capable CNC programming platform.

The main emphasis within the latest release of ArtCAM has been on improved strategies for harder materials to enable more efficient and faster engraving of metal tooling. Typical applications that will benefit include the engraving of decorations, logos and lettering into moulds, the manufacture of stamping dies for coins and medals, and the production of embossing dies for cards, packaging and book covers. In addition, the machining simulations have been made much more realistic as part of a general improvement in the ability to visualise designs in a variety of materials.

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Delcam's ArtCAM Users to Meet in Kansas City

1 July 2009

Delcam will hold its 2009 ArtCAM User Group Meeting at the Crowne Plaza Hotel, Kansas City, from 30th September to 2nd October. The event will open with a special networking evening at Hallmark Cards, one of the largest ArtCAM users in North America. This will be followed by two days of workshops on the latest versions of the software.

In today's economy, everyone is looking for ways to be more competitive and more profitable. With this in mind, Delcam has decided to focus on ways of improving skill level and productivity at the meeting. The first day will be a general session covering core modelling functionality, 2D & 3D design styles, tips and tricks and what's to come in the 2010 version of ArtCAM. "Already used by many signmakers, cabinet-makers, and furniture manufacturers, this new version is set to further increase the use of ArtCAM in the three-dimensional world," said Ed Powell, ArtCAM Product Manager.

ArtCAM 2010 will include a new modernised graphical user interface, direct interactivity and improvements to the core performance by utilizing GPU Acceleration and CPU multi-threading. As with previous versions, ArtCAM development continues to be designed around simplifying the workflow so that even beginners to CNC technology can start using the program as quickly as possible. More advanced users will appreciate the direct 3D interaction and the ability to customise their favourite toolsets.

The use of multi-threading will enhance the toolpath calculation performance making ArtCAM even

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faster and more efficient. In addition toolpath strategies can now be associated with vector layers, making it easier to machine complicated nested patterns.

The second day will be focused to specific industries and the related software. “We believe the second day split is the best way for our delegates to effectively make use of the time they have available,” said Mary Shaw, Delcam Marketing Manager. “This year during this time we will be looking at the most practical combination of techniques and ideas to transform and improve what you can do with ArtCAM.”

“Both new and experienced users are often amazed how much they can learn by attending the User Group and learning from real world experience and expertise that is available,” added Ms. Shaw. “As well as learning from the Delcam ArtCAM team, probably the best reason to attend a User Group is to meet other users of ArtCAM and learn from them.”

Like the online forum, the User Group is an opportunity to catch up with friends, find out about other equipment and materials and be inspired by the different uses and applications on show from ArtCAM customers. “Delegates will learn a lot about what is possible for them to achieve and be motivated when they return to their businesses to make ArtCAM an even more productive part of it,” said Ms. Shaw.

Once again, there will be a design competition in conjunction with the User Group. “We will once again be opening up the floor to our users to show us some of the excellent projects they’ve been working on,” explained Ms. Shaw. Categories will be judged based on industry and product type with the prizes and winners being announced during the User Group. Entries for the competition can be submitted at www.artcam.com/promos/ug2009/index.htm

For more information on the ArtCAM User Meeting, call the Delcam North American office at 1 877 335 2261 or email Jackie at jackie@delcam.com.

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ESPRIT at Difficult Manufacturing Technology Show 2009, Nagoya, Japan, July 2-4

26 June 2009

The latest version of computer-aided-manufacturing (CAM) software created by [DP Technology](#) will be on display July 2-4 in Nagoya, Japan, where ESPRIT® will be featured at Difficult Manufacturing Technology Show, or DMTS, 2009.

Slated to take place at Port Messe Nagoya, the annual show is a vehicle for the exploration and discovery of complex manufacturing methods. Featuring the newest technologies, the event covers machinery and metals, as well as industrial, manufacturing and engineering technologies.

Knowledgeable and approachable representatives of ESPRIT will be on hand to answer questions and perform demonstrations of the latest time-saving software upgrades.

Designed with ease of use in mind, ESPRIT emphasizes the use of milling or turning in any combination and on any type of machine tool, which means that most improvements to the software are to the benefit of all programmers.

A new concept in highly-advanced machining functionality is based on the idea that any five-axis machining function, no matter how complex, can be defined with a few simple steps. By following the same time-tested steps that programmers use when deciding how to machine 5-axis parts, an advanced CAD/CAM system can combine highly advanced milling technology with an interface that is familiar

and easy to understand.

The new patent-pending FreeForm 5-axis composite machining cycle in ESPRIT allows users to independently define machining patterns and tool orientation strategies to be used when creating the simultaneous 5-axis tool path, and includes 20 different machining strategies (cycles) in one, resulting in a wide range of easily manageable possibilities. The new ESPRIT composite machining cycle gives the user the ability to perform simultaneous 5-axis machining for a wide variety of different parts and industries, including aerospace, medical, and automotive, through one simple user interface.

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46th Design Automation Conference Management Day Provides Timely Insights and Valuable Interaction with Industry Peers

29 June 2009

The Design Automation Conference (DAC) will once again offer a special Management Day Tuesday, July 28 to provide managers with timely information to help them make decisions where business and technology intersect. Management Day, which this year is sponsored by Cadence Design Systems, Inc., will be organized into three sessions focused on the business and technology criteria managers need to consider as they deal with the development of today's complex SoCs. Two sessions will feature managers from leading independent device manufacturers (IDMs), fab-light ASIC providers and fabless companies, while the final session will be an interactive panel discussion and brainstorming session about the emerging solutions discussed and their economic impact. A cocktail reception will end the day. The 46th DAC will be held July 26 – 31 at the Moscone Center in San Francisco.

“Managers in the electronics industry face increasing challenges as they navigate the complex technology and business landscape,” said Yervant Zorian, Virage Logic Corp. and EDA Industry Chair, DAC Executive Committee and the organizer of Management Day. “Management Day at DAC will give participants the opportunity to hear from peers in the industry and learn how their teams are addressing these challenges and exchange ideas on potential solutions.”

Management Day will begin at 10:30 a.m. with “Trade-Offs and Choices for Emerging SOCs,” chaired by Nic Mokhoff, of EE Times/TechInsights. Rani Borkar, Vice President Digital Enterprise Group, Intel Corp.; Philippe Magarshack, Vice President Central R&D, STMicroelectronics; and Don Friedberg, Director, Network & Storage Products Group, LSI Logic Corp. will each address challenges surrounding today's most complex nanometer chips.

After lunch, the second session, “Decision Making for Complex SOCs,” from 2 – 4 p.m. will be chaired by Ed Sperling of System Level Design and feature presentations by Alan Nakamoto, Vice President Engineering & Founder, PMC-Sierra, Inc.; Pierre Garnier, Vice President & General Manager Worldwide Wireless Baseband, Texas Instruments, Inc.; Christoph Heer, Vice President Digital IP & Re-Use, Infineon Technologies AG; and Ed Nuckolls, Austin IC R&D, Freescale Semiconductor, Inc. The session will cover the challenges of complex SOC design and present corresponding management decision criteria that allow managers to make the right choices from a pool of alternate options.

The final session, from 4:30 – 5:30 p.m., will be a panel discussion on “Making Critical Decisions for Emerging SOC Development,” moderated by Peggy Aycinena, EDA Confidential. Albert Li, Director, Global Unichip Corp. will begin the session with his presentation, “Trade-Off Analysis in Complex SOC Designs”. Then, all of the day's presenters will participate in this interactive panel discussion that will be the culmination of the ideas presented and exchanged throughout the day.

Registration

The registration fee for Management Day is \$95 and includes coffee breaks and cocktail reception. The advance conference registration discount deadline for the 46th DAC is June 29, 2009. For more details on DAC's full program, and to register, please visit <http://www.dac.com>.

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SoftInWay Has Scheduled Educational Events for Engineers for July-December 2009

1 July 2009

SoftInWay Inc. has announced its educational activities for the second part of 2009. To meet the growing demand on training programs for mechanical and aerospace engineers, the company will be conducting professional turbomachinery design courses in 6 countries worldwide.

Thus, SoftInWay has scheduled AxSTREAM Introductory seminars during which the company's team will bring in the features of AxSTREAM – software system for design, analysis and multidisciplinary optimization of turbomachinery flow path. The seminar is dedicated to engineers involved in turbomachinery design and/or retrofitting, as well as to students of technical faculties and their professors.

Such seminars will be held

- July 14 in Bangalore (India);
- October 16 in Tokyo (Japan);
- October 19 in Beijing (China).

To provide the engineering community with the necessary knowledge and hands-on experience, SoftInWay presents a new 5-day integrated course on axial turbine basics and turbomachinery design with AxSTREAM.

The program consists of two independent parts. The Axial Turbine Fundamentals course (2 days) describes gas dynamics, thermodynamics, structural analysis and essentials of axial turbines and their elements. “A most useful and interesting educational course backed up by excellent course text with helpful examples, – admitted Nathan Abbott, Dresser-Rand. – The course content covered all of the basic turbine fundamentals and was delivered at a pace that allowed the information to be digested ensuring a full understanding. The lecturers were extremely helpful and were more than willing to answer any questions.”

The second part – AxSTREAM Interactive Workshop on Turbomachinery Design and Optimization (3 days) – is focused on practical aspects of design, optimization and retrofitting of axial/radial/mixed flow turbomachinery. After the workshop all the participants will be granted a free 1-month license for AxSTREAM.

The 5-day intensive course on turbomachinery will take place

- September 21-25 in Dusseldorf (Germany);
- October 2-6 in Bangkok (Thailand);
- November 9-13 in Boston (MA, USA), (presentation of AxSTREAM 3.0).

Finally, to make its educational programs even more available and reach engineers all over the world,

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SoftInWay offers free monthly webinars powered by the company's industry experts. The next webinar on multidisciplinary optimization of turbomachinery flow path using Design of Experiment and Low Discrepancy Sequences methods will be held

- July 23, at 10 a.m. and 4 p.m. EST.

To register for SoftInWay educational programs or to find more detailed information, please visit <http://softinway.com>.

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Financial News

Aspen Technology Announces Financial Results for the Fourth Quarter and Fiscal Year 2008

30 June 2009

Aspen Technology, Inc. announced financial results for the fourth quarter and fiscal year 2008, ended June 30, 2008.

Mark Fusco, Chief Executive Officer of AspenTech, said "The company delivered a strong operational performance in fiscal 2008, highlighted by annual license bookings growth of over 15% and record cash flows from operations." Fusco added, "We are pleased to achieve another milestone related to bringing the company's financial statements current. We have now completed our first audit process and Annual Report on Form 10-K with KPMG, and we are executing against plans to finish our fiscal 2009 reports as quickly as possible."

Income Statement for Fourth Quarter of Fiscal 2008

For the fourth quarter ended June 30, 2008, AspenTech reported total revenue of \$98.3 million, a decrease of 3% compared to the fourth quarter of fiscal 2007. Within total revenue, license revenue was \$59.7 million, a decrease of 12%, and services revenue was \$38.6 million, an increase of 15%, both compared to the fourth quarter of fiscal 2007.

During the fourth quarter of fiscal 2008, the company entered into three contracts with a net present value totaling \$12.5 million that did not meet all of the criteria for revenue recognition as of the end of the quarter. There was not a comparable impact on the prior year period. As previously disclosed, license bookings were approximately \$70 million in the fourth quarter of fiscal 2008, up slightly compared to the fourth quarter of fiscal 2007.

AspenTech's income from operations, determined in accordance with generally accepted accounting principles (GAAP), was \$21.1 million in the fourth quarter of fiscal 2008, representing an operating margin of 21.4%, compared to \$24.0 million in the fourth quarter of fiscal 2007.

Net income was \$20.7 million for the fourth quarter of fiscal 2008, compared to \$17.9 million for the fourth quarter of fiscal 2007. Diluted income per share attributable to common shareholders was \$0.22 for the quarter ended June 30, 2008, three cents better than the fourth quarter of fiscal 2007.

Income Statement for the Full Year Fiscal 2008

For the fiscal year ended June 30, 2008, AspenTech reported total revenue of \$311.6 million, a decrease of 9% compared to fiscal 2007. Within total revenue, license revenue was \$168.4 million, a decrease of 16%, and services revenue was \$143.2 million, an increase of 1%, both compared to the full fiscal year

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2007.

During fiscal 2008, the company entered into seven contracts with a net present value totaling approximately \$57.5 million that did not meet all of the criteria for revenue recognition as of the end of the fiscal year. There was no comparable impact on the prior fiscal year period.

AspenTech's income from operations, determined in accordance with generally accepted accounting principles (GAAP), was \$18.6 million for fiscal 2008, representing an operating margin of 6%, compared to \$55.4 million for fiscal 2007.

Net income was \$24.9 million for fiscal 2008, compared to \$45.5 million for fiscal 2007. Diluted income per share attributable to common shareholders was \$0.27 for fiscal 2008, compared to \$0.50 for fiscal 2007.

Balance Sheet and Cash Flow

The company's cash balance at the end of fiscal 2008 was approximately \$134 million, an increase compared to approximately \$132 million at the end of fiscal 2007. Cash flow from operations was \$70.8 million during fiscal 2008, offset by cash used in investing activities of \$9.8 million and cash used in financing activities of \$59.8 million.

Total company-owned accounts and installments receivable balances were \$221.2 million at the end of fiscal 2008, an increase of \$131.1 million from \$90.0 million at the end of fiscal 2007. The company's secured borrowings balance at the end of fiscal 2008 was \$147.2 million, a reduction of \$58.9 million from \$206.1 million at the end of fiscal 2007.

The company's total deferred revenue balance at June 30, 2008, was \$106.9 million, an increase of 59% compared to the end of fiscal 2007.

Conference Call and Webcast

AspenTech will host a conference call and webcast tomorrow, July 1, 2009, at 8:30 am (Eastern Time) to discuss the Company's fourth quarter 2008 financial results and related corporate and financial matters. The live dial-in number is (877) 239-3024, conference ID code 17469720. Interested parties may also listen to a live webcast of the call by logging on to the Investor Relations section of AspenTech's website, <http://www.aspentech.com/corporate/investor.cfm>, and clicking on the "webcast" link. A replay of the call will be archived on AspenTech's website and will also be available via telephone at (800) 642-1687 or (706) 645-9291, conference ID code 17469720 through July 8, 2009.

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Cranes Software's FY09 Consolidated Revenues up 33% to Rs. 5,289 Million and PAT Higher by 6% to Rs. 1,213.1 Million

1 July 2009

- FY09 Diluted EPS at Rs. 9.36
- Recommends dividends of 10%
- Shifting of Cranes Engineering and Cranes Technology operations to 35,000 sq ft

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of own office premises expected to result in considerable savings

Cranes Software International Ltd. (Cranes), a Company that provides Enterprise Statistical Analytics and Engineering Simulation Software Products and Solutions across the globe, announced its audited financial results for the quarter and year ended March 31, 2009.

Cranes Software Group's financial performance review:

Corresponding Yearly Comparison

FY09 (April – March 2009) v/s FY08 (April – March 2008)

Total revenues were up 32.7% to Rs. 5,289 million from Rs. 3,986 million

Overseas revenues increased 41.0% to Rs. 4,509 million and constitute 88.6% of total revenues

Domestic revenues at Rs. 579 million for the period under review

Operating profit improved by 17.9% to Rs. 2,402 million from Rs. 2,038 million. Operating margins for the year at 45.4%

Net profit after tax is up 5.5% to Rs. 1,213 million from Rs. 1,150 million. Accordingly, diluted EPS grew 5.8% from Rs. 8.85 to Rs. 9.36 for the period under review

Corresponding Quarterly Comparison

Q4 FY09 (January – March 2009) v/s Q4 FY08 (January – March 2008)

Total revenues higher by 50.0% to Rs. 1,765 million compared to Rs. 1,177 million in the previous corresponding quarter

Overseas revenues increased by 61.3% to Rs. 1,475 million and constitutes 94.0% of total revenues

Operating profit was up 25.8% to Rs. 639 million from Rs. 508 million. Operating margins were at 36.2% for the quarter ended March 2009

Net profit after tax fell 11.5% to Rs. 281 million translating into diluted EPS of Rs. 2.15 for the quarter under review

Commenting on the financial results, Asif Khader, Managing Director, Cranes Software International Limited, said:

“For the year ended March 2009, Cranes Software has registered a growth of 33% in revenues (including inorganic) to Rs. 5,289 million while PAT grew by 6% to Rs. 1,213 million. This year also witnessed a historic and unprecedented global financial instability that has led many Companies, including ours, to realign the business offerings to suit the current challenging environment. We had to take strict measures in terms of cleaning the supply chain and curtailing costs to maintain efficiencies. Our business continues to remain robust, although reflective of current economic realities, we also did and do face challenges, particularly in regard to customer collections. We believe this to be an interim phenomenon and have adopted effective strategies to counter these. During the year, we entered into alliances with several leading Companies and announced new product launches that will serve as a

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platform for our future growth initiatives. Going forward, we will continue to focus on consolidating operations to sustain long term growth and with increased emphasis on productivity of resources.”

Other Highlights:

Cranes Software’s premier graphing application, SigmaPlot 11 won the Scientific Computing Magazine's Reader's Choice Award 2008 in the 'Graphing' and 'Statistical Analysis' categories. The latest release of its kind by Systat Software, SigmaPlot is an advanced scientific graphing and data analysis software that allows its users to present their data using exact, publication-quality graphs.

Cranes Software shifted its Engineering and Technology operations to own premises. This state of art campus built over 35,000 sq ft. has an exclusive parking area of 7,300 sq ft, a spacious cafeteria of 5,300 sq ft, and a full fledge communication center with sophisticated and innovative communication solutions that could enable speedy and cost effective communication to onsite employees and global customers.

Board recommends a dividend of 10% (Rs. 0.20/- per share)

Acquisitions & Alliances during the Year under review:

Cranes Software’s subsidiary, Proland Software, a data security company, entered into a strategic partnership with VirusBuster, a Hungary-based security solutions provider. This alliance will enable Proland to provide a wider selection of data security solutions to its customers, and expand its presence from a predominantly home/single user base to the enterprise/office segments

Cranes’ subsidiary, Systat Software entered into an agreement with Ohio based Rescentris, to globally offer their joint product, SigmaCERF - an Electronic Lab Notebook (ELN) and knowledge management platform for life science research organizations. While industry experts predict the market for ELN to be one of the fastest technology growth areas, this collaboration will also enable Cranes’ SigmaPlot, SigmaStat and Systat customers to source tools that cater to different aspects of their research process from one single reliable source

Cranes entered into an alliance with Siemens PLM Software, a business unit of the Siemens Industry Automation Division and a leading global provider of product lifecycle management (PLM) software and services. This partnership will enable Cranes to distribute the full suite of PLM software solutions to its customer base in India, thereby strengthening its position further in the engineering simulations space

Cranes’ subsidiary, Systat Software successfully acquired a German-based business intelligence product Company, Cubeware. The acquisition will draw multi fold synergies in the real time business intelligence and performance management space for enterprise business applications

New Product Launches during the Year under review:

Released ETA/DYNAFORM Version 5.7 – With over 90 new and enhanced features, the latest launch of its powerful die analysis solution, ETA/DYNAFORM Version 5.7 will further address some of the long standing requirements of the Manufacturing and Automobile sectors

Launched NISA DesignStudio Version 16 - A Civil Engineering software, NISA DesignStudio is a cost-effective software solution for individual and upcoming structural engineers who predominantly analyze and design multistoried buildings, apartment complexes and industrial enclosures made of RCC & steel

Launched NISA Version 16 for Linux – With over 40 new features and a significant improvement over its predecessor, NISA Version 16 for Linux will give the Company deeper entrants into the Computer Aided Engineering (CAE) industry

Released ETA/VPG Version 3.4 with NISA Solver – A finite element modeling software, ETA/VPG Version 3.4 has over 63 new or improved functions and offers an integrated linear static and Eigen value modules from the general purpose FEA software suite NISA, which allows users to easily create and visualize advanced simulations within the ETA/VPG environment

For full financials please visit <http://www.cranessoftware.com/press/press-releases/125.html>

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Implementation Investments

Aquantia Deploys Synopsys IC Validator and IC Compiler for 40nm Quad 10GBASE-T Design

29 June 2009

[Synopsys, Inc.](#) announced that Aquantia, a leading innovator in 10GBASE-T networking, has deployed Synopsys' recently announced IC Validator, the newest addition to the Galaxy™ Implementation Platform, into production use at 40 nanometers (nm). IC Validator is an ideal add-on to IC Compiler for In-Design physical verification, enabling place and route engineers to accelerate time to tapeout and improve manufacturability by enabling physical verification within the implementation flow. Compared to the typical implement-then-verify flow, the In-Design flow is instrumental in avoiding late-stage surprises and enabling integrated circuit (IC) providers like Aquantia - which is in the process of delivering an advanced 40nm-based quad 10GBASE-T solution - to achieve a faster, robust hand-off to the foundry.

"A few weeks can mean the difference between meeting or missing the market window in our fast moving market," said Ramin Shirani, vice president of engineering at Aquantia. "IC Validator's ability to perform In-Design physical verification within IC Compiler reduces the physical verification effort from weeks to days by automating and accelerating one of the most onerous parts of our design cycle. We were impressed by IC Validator's fast convergence in concurrently implementing signoff metal-fill and DRC while reducing the timing impact of such implementation."

Prevailing physical verification flows are predominantly post-processing oriented, relying on modifications to the design after GDSII has been generated. These flows can lead to suboptimal results and can induce multiple discover-then-fix iterations. Metal-fill insertion, a mandatory manufacturability step at the advanced nodes, exemplifies this issue. Physical designers stream out the timing-closed, post-fill design for signoff validation and then stream it back in to fix any signoff errors flagged during physical verification. This time-intensive discover-then-fix loop is typically repeated on each block until the post-fill design is both signoff qualified and timing clean.

With In-Design physical verification, IC Validator and IC Compiler address the manufacturability issues within the place and route environment. The seamless integration enables an optimal metal-fill flow that is timing aware, signoff quality and void of expensive stream-outs and stream-ins. Additionally, this flow achieves higher density by utilizing a track-less approach.

While In-Design physical verification is enabled through tight integration with place and route, it is founded on a high-performance, foundry-endorsed, signoff-accurate engine in IC Validator. With a native multicore architecture, IC Validator can significantly accelerate the metal-fill process by up to 20 times. For incremental fixes to metal fill near critical nets or ECOs, the In-Design flow enables rule-based, layer-based and area-based metal fill removal and re-insertion, thereby helping eliminate the need

for costly full-chip runs.

"In-Design physical verification with IC Validator and IC Compiler is successfully addressing the increasing design-for-manufacturability needs of our customer base," said Saleem Haider, senior director of marketing, physical design and DFM at Synopsys. "For meeting foundry-dictated manufacturing needs, Aquantia's adoption of IC Validator demonstrates the value of placing the emphasis on the 'D' in DFM and handling manufacturability requirements during design instead of post-design modifications."

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Billabong Selects NGC for PLM and Global Sourcing

30 June 2009

[NGC](#)® (New Generation Computing®) announced that Billabong has selected NGC's e-PLM® for Product Lifecycle Management and e-SPS® for Global Sourcing and Visibility. NGC's software will be implemented worldwide as a strategic PLM and global sourcing solution for Billabong across all of the company's regions and brands.

Billabong selected NGC after a detailed and rigorous evaluation of the industry's leading PLM vendors. "We chose NGC based on the functionality and ease of use of their solutions, as well as NGC's deep understanding of the fashion and apparel industries," said Mike Savage, General Manager of Product Development, Billabong International Limited.

"Billabong is an exciting, dynamic company and one of the hottest brands in action-sports apparel," said Alan Brooks, President, NGC. "NGC is honored that we were selected by Billabong, and we look forward to a successful implementation."

About Billabong

Billabong International Limited's core business is the marketing, distribution, wholesaling and retailing of apparel, accessories, eyewear, wetsuits and hardgoods under the Billabong, Element, Von Zipper, Honolua Surf Company, Kustom, Palmers Surf, Nixon, Xcel, Tigerlily, Sector 9 and DaKine brands.

Billabong International's products are licensed and distributed in more than 100 countries and are available in approximately 10,000 doors worldwide. For more information, visit

<http://www.billabong.com>.

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Carl Zeiss Meditec Reduces New Product Introduction Cycle with PTC CoCreate

29 June 2009

[PTC](#) turns the spotlight on the success of the Cirrus™ HD-OCT – a high definition retinal scanner which has now been established as the new clinical standard for retinal care. This product was successfully launched ahead of schedule as a result of Carl Zeiss Meditec's product development process which uses PTC CoCreate explicit CAD software. CoCreate offers great flexibility at the innovation and design stage, and when coupled with PTC CoCreate Model Manager it provides efficient model sharing between engineers for concurrent design.

Carl Zeiss Meditec is a worldwide leading provider of system solutions to diagnose and treat eye

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disorders. The Cirrus HD-OCT high definition retinal scanner uses spectral domain technology to capture 3D line scans of the retina. The high resolution images allow better visualization and understanding of disease pathogens, assisting the examination of patients with retinal degenerations, uncommon macular disorders and glaucoma.

In order to accelerate the product's introduction to market the Carl Zeiss Meditec development team relied upon CoCreate as part of a complete 3D virtual prototyping process that allowed the team to eliminate one cycle of physical prototypes. As a result, the company introduced the Cirrus HD-OCT to market five months ahead of a typical development schedule. Carl Zeiss Meditec used CoCreate Modeling and its associativity with finite element modeling software packages to virtually prototype and optimize the thermally sensitive mounts for the optical components.

As is typical when developing new technology, the product development team had to adapt to evolving requirements. By using an explicit approach to 3D product development, Carl Zeiss Meditec was able to quickly and easily adapt the original design. Additionally, the company automated its data management processes by using CoCreate Model Manager to extend the use of the 3D product data to downstream departments, ensuring that its manufacturing, procurement and supply chain departments had controlled access to the most up-to-date product design data.

“The flexibility of CoCreate 3D modeling allowed the engineers to be creative, which enabled us to develop a novel and extremely compact instrument in a shorter than usual schedule” said Chris Baker, director of mechanical engineering, Carl Zeiss Meditec. “CoCreate Model Manager made it easy to access and reuse existing components on this project while ensuring that engineers always had the latest part revisions during design.”

“Many customers like [Carl Zeiss Meditec](#) face short lead times and come from fast-paced industries where the ability to respond to unpredictable product and requirement changes is critical to their success,” said Martin Neumueller, director, product management, PTC. “The explicit modeling approach provided by CoCreate allows product development teams to quickly create and modify 3D product designs and provides flexibility to make unexpected and radical changes to a product design until late in the development process. This capability was critical to the success achieved by Carl Zeiss Meditec.”

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Catalog Data Solutions Selected by Northwestern Tools for Online CAD Downloads

30 June 2009

Catalog Data Solutions ([CDS](#)) announced that Northwestern Tools, Inc. has implemented its CAD Download solution to present and download product CAD models from [SpringAndBallPlungers.com](#).

The new [SpringAndBallPlungers.com](#) website was developed by [Reid Supply Company](#) and [Northwestern Tools](#) to provide designers direct access to a complete line of spring and ball plungers - spring plungers, ball plungers, hand retractable, press fits, modified standards, or complete specials, whatever your requirements.

“Adding CAD Downloads to our <http://www.SpringAndBallPlungers.com> web site will save our customers time in specifying and configuring our products for their designs,” said Bob Madewell of Northwestern Tools. “With this CAD support combined with the ease of ordering our products on-line we expect to see an increase in the number of online orders and RFQs.”

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“We are delighted to have been selected by Northwestern Tools for our leading online CAD model download solution”, said John Major, CEO Catalog Data Solutions, “online 3D models are an important sales and marketing tool for all industrial suppliers and distributors. With many customers moving from 2D to 3D CAD systems providing online 3D CAD model downloads saves customers time and often ‘locks’ products into a design. Conversely suppliers without 3D models on their website are at risk of losing customers to their competition who do offer 3D models”.

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Defense Group Saab Signs Corporate Agreement With IFS

26 June 2009

[Saab AB](#) has signed a corporate agreement with IFS to deepen the cooperation between the parties and to position the group for new business opportunities. The agreement covers licenses, consulting, support, and maintenance of IFS Applications for the entire group and has an estimated value of SKr 120 million over four years. The value of the licenses is approximately SKr 12 million, of which SKr 5 million are called off in June 2009.

Several companies within Saab currently use IFS Applications for after-sales services, design and manufacturing, MRO (Maintenance, Repair, and Overhaul), engineering, supply-chain management, and project management. Saab has been a customer of IFS since 1994 and has a long-term strategy of increasing its use of IFS Applications across the group to achieve greater efficiency within IT. One example is the business units that manufacture aerostructures and related sub-systems for commercial aviation as well as the military market such as the JAS Gripen, Saab Aerostructures, which in 2006 carried out a successful consolidation of 59 self-developed or customized systems into one common system—IFS Applications.

“We see great opportunities for similar synergies in the other business units within the Saab Group, and our strategy is to achieve a global standardization of processes and systems by 2013. We look forward to working with IFS to continue streamlining and rationalizing our operations based on a common business system”, Johan Sjödin, Vice President ICT Coordination Office at Saab AB, said.

As a corporate supplier, IFS gets a central role in assisting Saab to reach its business goals.

“The agreement will help us reach our goals both in terms of new revenues and savings. Now that many central business processes can become common, we get more mobility and flexibility as well as lower IT costs as a result of economies of scale” said Johan Sjödin. “IFS’ focus on the defense industry is positive. Their developers and consultants really listen to us and I look forward to the continued development of our collaboration and partnership”.

For IFS, collaboration with customers is critical for the continued improvement of the solutions.

“The industry solution for Aerospace and Defense is continuously developed in close cooperation with key customers like Saab and partners such as BAE Systems, Logica and EDS”, Glenn Arnesen, Managing Director of IFS Scandinavia said. "One of the primary areas for our 2009 research and development is to improve the functionality we deliver to the A&D segment."

IFS’ customers in aviation and defense include the British, Norwegian, and American defense. Commercial workshops and operators include Finnair, Bristow Helicopters, Aero-Dienst GmbH, Hawker Pacific, and LTQ Engineering Pty Limited (formerly knowns as Jet Turbine Services). In addition, IFS provides solutions to manufacturers such as the Eurofighter consortium, General

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Dynamics, Lockheed Martin, BAE Systems, Saab, and GE Transportation.

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Eyelit's Integrated Manufacturing Execution (MES) Software Selected by Umicore Electro-Optic Materials Division for Germanium Wafer Production

1 July 2009

[Eyelit, Inc.](#) announced that Belgium-based Umicore's Electro-Optic Materials Business Unit, has selected Eyelit's manufacturing software suite to support its germanium wafer production.

Eyelit and SYSTEMA GmbH, its European partner, were selected to deliver an integrated manufacturing execution and automation solution. Eyelit's solution replaces a paper-based system and provides reliable integration to SAP. Eyelit's system also provides a scalable solution with equipment management and product traceability, from raw material feedstock through to germanium ingot growth and wafer production. The project starts in Olen, Belgium with a rollout to Quapaw, Oklahoma in the second half of this year.

"We selected Eyelit because we needed a solution that we could easily expand across our global network of production sites. We wanted a proven solution that we could rely on well in the future, and have both European and US support capabilities. We felt that we could implement without custom code in order to gain competitive advantages rapidly. SYSTEMA's equipment integration and wafer manufacturing modeling experience were also critical factors in our selection," said Mr. Ludo Vermeiren, Business IT manager at Umicore's Electro-Optic Materials Division.

"SYSTEMA GmbH has a successful track record of providing automation and factory integration to our semiconductor and solar customers. Together with Eyelit's state-of-the-art manufacturing software suite, we can help our customers improve their operations and dramatically drive down the cost of manufacturing. We look forward to a successful engagement with Umicore," said Holm Fischer SYSTEMA's Senior Consultant Manager.

"We are continuing to gain MES market share with the help of partners like SYSTEMA. We've enjoyed a very successful relationship with SYSTEMA, found a niche in the semiconductor ingot growth area, recently added three new customers in the last five months. Whether it is concentrator solar cells (CPV), space solar cells, solar cells (PV), high-brightness LEDs or other various semiconductor applications, the manufacturing steps can all be modeled and managed within Eyelit's solution," stated Dan Estrada, Eyelit's Vice-President of Sales and Business Development.

About SYSTEMA GmbH

[SYSTEMA GmbH](#) is a leader in manufacturing systems integration for the semiconductor and photovoltaic industries. The company's products and services enable its customers to cost effectively integrate, automate, and optimize their production systems from Equipment Integration to Manufacturing Execution System to Enterprise Resource Planning. SYSTEMA'S product and service portfolio are built within a Service-Oriented Architecture, using industry-standard and open-source technology stacks. SYSTEMA's customers, such as AMD, Hewlett Packard, Infineon, Siltronic, Bosch, and Mikron, span the globe and are technology leaders within their fields. SYSTEMA GmbH is headquartered in Dresden, Germany with offices and partners in the USA and Asia.

About Umicore

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[Umicore](#) is a materials technology group. Its activities are centred on four business areas: Advanced Materials, Precious Metals Products and Catalysts, Precious Metals Services and Zinc Specialties. Each business area is divided into market-focused business units.

Umicore focuses on application areas where it knows its expertise in materials science, chemistry and metallurgy can make a real difference, be it in products that are essential to everyday life or those at the cutting edge of new technological developments. Umicore's overriding goal of sustainable value creation is based on this ambition to develop, produce and recycle materials in a way that fulfills its mission: materials for a better life.

The Umicore Group has industrial operations on all continents and serves a global customer base; it generated a turnover of € 9.2 billion in 2008 and employs some 15,000 people.

About Electro-Optic Materials

The business unit [Electro Optic Materials](#) of Umicore is a world leading supplier of Germanium based material solutions. The company supplies GeCL4 for the optical fiber industry, infrared optics for night vision applications and germanium substrates used in the production of LED's and high efficient solar cells for space and concentrator photovoltaic solutions. The Unit has operations in Europe (Belgium, UK and France) and the US.

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Hitachi Achieves 40% Reduction in PCB Place-and-Route Design Time With Cadence Global Route Environment

30 June 2009

[Cadence Design Systems, Inc.](#) announced that the Cadence® Global Route Environment (GRE) technology for Cadence Allegro® PCB design enabled Hitachi, Ltd. to successfully reduce printed circuit board (PCB) place-and-route design time by 40% for a high-speed communication product. Hitachi applied the GRE place-and-route design methodology to its PCB place-and-route from interconnect planning to complete routing, with full constraints for high-speed digital signals where no automation was previously available. The time-saving results were reported by Hitachi Communication Technologies, Ltd., the communication products division of Hitachi Group, as part of a companywide initiative at Hitachi to enhance design efficiency and reduce design-cycle time.

“High-speed PCBs require significant enhancements in performance, and gigahertz-level signals are becoming common,” said Toru Hiyama, general manager, MONOZUKURI Innovation Operation, Hardware MONOZUKURI Division at Hitachi. “Hitachi is always aiming at high-performance, high-quality products, and in order to complete the design in the shortest cycle time possible while maintaining high quality, it was critical for us to solve the bottleneck of place-and-route for PCBs. By using Cadence GRE technology, we can solve the routing bottleneck as well as enhance the reliability of the design.”

The Cadence GRE technology is the next-generation interconnect planning and routing technology for PCB, and establishes a new PCB design paradigm. The GRE technology provides users with automation for various stages of interconnect planning and routing where no automation has been available. At the beginning of the process it allows users to plan the routing strategy at a high-level through Interconnect Flow Designer. Through the Interconnect Feasibility capability it checks and provides feedback on available space for each of the flows, allowing users to modify their routing strategy. In the middle of

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the planning process, it determines the overall routing feasibility, including the routing paths, net topologies and assigned electric constraints. In the final planning phase, the GRE technology performs feasibility routing against the pre-determined routing flow, and then automatically completes routing. This approach becomes very effective for memory interfaces such as DDR2, DDR3, and serial interfaces such as PCI Express and PCI Express Gen II with their stringent high-speed design constraints.

At Hitachi, automatic routing had not previously been available to route signals with high-speed constraints. The GRE technology dramatically improves the quality of PCB designs by enabling users to concurrently work on the placement and the exploration of the routing strategies and paths. With GRE, Hitachi was able to effectively manage PCB designs with various tradeoffs. Hitachi expects further reduction of design time as the GRE performance and features are updated and further enhanced.

In March 2007, Hitachi and Cadence jointly announced that Hitachi had standardized on Cadence EDA products in order to enhance design efficiency and reduce the design-cycle time for Hitachi's hardware products as part of its focus on the company's manufacturing capability.

“Cadence GRE technology is the next generation of PCB interconnect planning and routing technology. It offers automation for designs with high-speed interfaces such as DDR2, SATA, and PCI Express,” said AJ Incorvaia, vice president of research & development, Allegro - R&D Development at Cadence. “In order to design today’s PCBs with high-speed constraints while maintaining quality levels like those of Hitachi, it is imperative to make route strategy trade-offs at early stages of design as well as have a unified and global methodology for routing. By combining their high-level requirements PCB design with GRE technology, Hitachi is able to significantly shorten their overall PCB design cycle. This success will become a standard reference for a new design methodology for high-speed PCBs.”

In addition to the full-constraints routing capability, Hitachi said the GRE technology will be effective for many other PCB design challenges, such as engineering changes and routing estimation. Hitachi plans to deploy and promote the GRE technology as a standard solution throughout the design environment.

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Renault Chooses Dassault Systèmes Full V6 PLM to Improve the Company’s Productivity and Product Quality

29 June 2009

Renault has selected [Dassault Systèmes](#)’ V6 PLM (Product Lifecycle Management) as its new global product development solution, in order to improve productivity, and product quality.

Renault has already started to implement the ENOVIA V6 based collaborative platform and CATIA V6, and will rapidly move to the full DS V6 portfolio to enable the company and its suppliers to collaborate on the creation of new product designs in real time.

Renault will deploy V6 PLM in all geographies and throughout all brands. The online access to the digital mock-up (DMU) will lead to a simplification of the collaboration between engineering sites. This use of a unique, collaborative interface for all developers worldwide supports simultaneous product/process engineering to get it ‘right the first time’.

Renault’s original engineering processes, divided into three different silos with three different solutions, will be transformed with a unified collaborative platform using a single, standardized data model, and solutions that are deployable “out of the box” for all engineering divisions. At the heart of Renault’s

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strategy to transform its product development is the V6 platform's virtualization of the entire product lifecycle within a truly collaborative environment that is both flexible and precise. Other requirements were the need to reinforce collaboration with extended enterprise partners and suppliers and to ensure iso-performance and data consistency between globally dispersed teams.

In DS's V6 solution, Renault found an integrated and collaborative PLM environment allowing more operational transparency and the possibility to validate scenarios through virtual simulation and online management of the DMU. This will significantly ease decision making throughout the stakeholder community and across the entire product lifecycle of Renault automobiles, from conception through design, compliance, simulation, and manufacturing.

"In the coming years, we will develop collaborative engineering. The partnership with Dassault Systèmes will contribute to this strategy. We chose the V6 platform because its integrated PLM environment brings our global teams together through real-time collaboration and online-enabled design anywhere," said Odile Desforges, EVP engineering and quality, Renault. "We have chosen to deploy the full V6 solutions portfolio, simply because it offers a remarkable collaborative, scalable, open and easy-to-use solution."

"Dassault Systèmes and Renault share the same vision of sustainable innovation through global collaborative product development. The automotive industry needs to consider economical and social aspects more than ever to make sure they create the vehicle that perfectly meets the customer needs and values. All stakeholders must be actors of the process of sustainable innovation," explains Bernard Charlès, president and CEO, Dassault Systèmes.

About Renault

The Renault Group generated global revenues of €37,791 million in 2008. It designs, engineers, manufactures and sells passenger and light commercial vehicles throughout the world. The Renault Group is present in 118 countries and sells vehicles under its three brands - Renault, Dacia and Samsung. The Renault Group employs 129,000 people worldwide.

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Synopsys MVSIM Adopted for Low Power Verification of STw8500 Mobile SoC Platform

1 July 2009

Synopsys, Inc. announced that ST-Ericsson has adopted Synopsys' MVSIM low power dynamic verification solution for its STw8500 system-on-chip (SoC) platform for the mobile phone market. ST-Ericsson selected MVSIM for its ability to comprehensively verify low power techniques, including standby and built-in automated low power assertions, which enable the early detection of bugs. The tool's extensive support for the IEEE 1801 [Unified Power Format (UPF)] power format, on which the STw8500 project team has standardized, was also a deciding factor.

"Mobile handset applications are driven by battery life, which necessitates the application of complex low power design techniques," said Francois Martin, director of the Wireless Multimedia Digital SoC's Business Unit at ST-Ericsson. "We chose MVSIM because of its ability to comprehensively verify the advanced low power techniques we employ for our wireless designs and detect bugs early in our design cycle."

The voltage-level aware simulation in MVSIM enables accurate verification of low power designs and improves bug detection. Its comprehensive set of built-in, automated low power assertions boost

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verification productivity. MVSIM, a core component of Synopsys' Eclipse™ Low Power Solution, is production-proven and works at the RTL and gate levels. MVSIM addresses complex low power verification challenges and enables customers to achieve their high-quality goals while meeting time-to-market constraints.

"The mobile phone market imposes some of the most stringent requirements on power and therefore demands the most advanced low power verification solution," said Swami Venkat senior director of functional verification marketing at [Synopsys](#). "Synopsys continues to pioneer tools and methodologies to help address low power verification challenges, including the recent publication of the Verification Methodology Manual for Low Power (VMM-LP) book. ST-Ericsson's adoption of MVSIM confirms the tool's growing momentum in the mobile market segment."

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Virage Logic Sees Strong Adoption of Company's Broad 40nm IP Product Portfolio

30 June 2009

Virage Logic Corporation announced that since being named TSMC's 40-nanometer (nm) early development partner in 2007, the company has seen strong adoption of its extensive 40nm product portfolio. Comprising embedded SRAMS, embedded memory test and repair, logic libraries, and memory development software, the Company's silicon-proven 40nm product offering has been designed to optimize area, performance, power and yield. Today, more than ten customers rely on Virage Logic's 40nm product portfolio to design more efficient chips more quickly and with less risk as they develop products for such end markets as graphics, consumer, enterprise, networking, wireless, and handheld.

"Virage Logic has a long, proven track record of being first-to-market at the advanced process technologies and with our extensive 40nm product portfolio, we are proud to offer our customers a competitive advantage at this advanced process node," said Brani Buric, Virage Logic's executive vice president, marketing and sales. "Our [SiWare\(TM\) Memory](#) and [SiWare\(TM\) Logic](#) products provide designers with a comprehensive dashboard of options for the flexibility needed to efficiently manage design tradeoffs and meet customers' specific requirements. For example, this dashboard enables our customers to achieve up to a 90% power savings in 40nm G and LP process nodes. Our [STAR\(TM\) Memory System](#) embedded test and repair offering extends the value we can deliver by enabling customers to dramatically ramp to volume at advanced nodes such as 40nm," he said. "Finally, our product portfolio is supported by a range of engagement models to best meet the requirements of our fabless, integrated device manufacturer (IDM) and foundry customers."

"TSMC selected Virage Logic as an early development partner at 40nm as a continuation of our collaboration in technologies ranging from 250nm to 40nm. Virage Logic and TSMC work closely to qualify IP through both Virage Logic's procedures and TSMC's procedures including silicon validation of these advanced technology IP solutions," said Dan Kochpatcharin, deputy director, IP Portfolio Marketing at TSMC. "These extensive silicon quality report results are available to designers of advanced SoCs for review when choosing Virage Logic's broad IP portfolio on TSMC's 40nm process."

"We have been working with Virage Logic to meet our customer's 40nm ultra-low-power SoC requirements," said Prasad Subramaniam, vice president of design technology at eSilicon Corporation. "By utilizing Virage Logic's SiWare Memory product line, we expect to be able to provide our customers with a competitive advantage that includes first time silicon success and accelerated time-to-volume production."

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"With the inclusion of Virage Logic's 40nm SiWare Memory compilers as part of our overall LSI 40nm Memory capability, LSI has continued its partnership with Virage Logic," said Don Friedberg, director of foundation IP at LSI. "We are using Virage Logic's feature-rich IP, including embedded memories for power minimization and the STAR Memory System for embedded memory built-in test and repair, to develop solutions that meet our customers' quality and performance requirements."

"Virage Logic is an essential IP partner, spanning four process generations from 130nm to 40nm," said Shai Cohen, co-founder, vice president of operations and engineering at Mellanox Technologies. "With their commitment to technology leadership and quality, Virage Logic ensures we consistently achieve first time silicon success, which is a tremendous competitive advantage for our industry-leading, performance end-to-end connectivity solutions for the high-performance computing and enterprise data center markets."

"We first selected Virage Logic's 65nm SiWare Memory offering because it provided the best power and density specs to meet our stringent design requirements. We also took advantage of the compiler configurability for performance optimization and the STAR Memory System for testability," said Bradley Masters, vice president of engineering for Solarflare Communications. "With the availability of even more power management capabilities in the 40nm SiWare Memory products, the choice to move to 40nm with Virage Logic was easy. We are confident that our forthcoming 40nm 10GBASE-T transceiver products will be very robust with very compelling low levels of power consumption."

About Virage Logic's Memory and Logic Products

The SiWare product line, first introduced in October 2007 for the 65nm process, has been proven to address the increasingly complex design requirements that are placed on physical IP at advanced processes. The power-optimized memories for advanced processes minimize both static and dynamic power consumption and provide optimal yields. SiWare High-Density memory compilers are optimized to generate memories with the absolute minimum area. SiWare High-Speed memory compilers are designed to help designers achieve the most aggressive critical path requirements. Compile-time options for process threshold variants, power saving modes, read and write margin extensions, ultra-low voltage operation, and innovative design for at-speed test enable SoC designers to configure optimal solutions for their specific design requirements.

All SiWare memories are fully supported by Virage Logic's STAR Memory System, the company's flagship embedded memory test and repair system that may be used with Virage Logic memories as well as with other commercially available or internally developed memories. For repair purposes, the STAR Memory System deploys foundry-developed eFuse for repair signature storage. The STAR Memory System employs test algorithms tailored for advanced processes for higher product reliability and accelerated time-to-yield.

The SiWare Logic product line includes yield-optimized standard cells for a wide variety of design applications at 40nm with multiple threshold process variants. SiWare Logic libraries offer three separate architectures to optimize circuits for Ultra-High-Density, High-Speed, or general use. SiWare Logic Ultra-Low-Power extension libraries also provide designers with the most advanced power management capabilities.

For further information about Virage Logic's silicon-proven 40nm product portfolio, or to request silicon validation reports, please visit www.viragelogic.com/SurePathTo40nmSuccess or email Virage Logic at info@viragelogic.com.

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Worldwide Aerospace Supplier, LISI AEROSPACE, Chooses HyperWorks to Streamline Development Processes for Fastener Systems

29 June 2009

[Altair Engineering, Inc.](http://www.altair.com) announced that LISI AEROSPACE (<http://www.lisi-aerospace.com>), one of the leading providers of aeronautical fasteners and assembly components, has chosen the HyperWorks simulation platform in combination with its non linear simulation tools to reduce the time needed to develop new fastener systems.

"When selecting a new CAE product suite, we were strongly focused on finding a powerful toolset that would streamline our pre- and post-processing activities," said Antoine Villet, FEA simulation engineer, LISI AEROSPACE. "In HyperWorks we found the tool suite we were looking for and throughout the entire benchmark and selection process Altair's support was outstanding. HyperWorks modeling and visualization solutions, HyperMesh and HyperView, best suited our needs allowing us to model our components more accurately and faster. The open architecture of the software family is an additional plus since it allows us to use our component models with any type of solver that might be required."

LISI AEROSPACE aggressively pursues using more simulation throughout their development processes. With their selection of HyperWorks, they will use HyperMesh to streamline the creation of finite element models to support their forging simulation processes. The broad range of HyperMesh algorithms for surface and volume meshing will help to drive future development activities at LISI AEROSPACE. HyperView, the HyperWorks post-processing solution, will be used for results visualization and automating reporting tasks.

"The close cooperation with LISI engineers during this benchmark allowed us to gain a much deeper understanding of their development processes, allowing our customer support team to really highlight core HyperWorks functionality to meet their needs and objectives," said Mauro Guglielminotti, regional manager, Altair Engineering France. "This win is consistent with the growing adoption of HyperWorks that we see in the French aerospace industry. As the Lisi benchmark proved, the combination of our CAE technology, flexible licensing system, and open architecture software philosophy makes a compelling argument for manufacturers seeking a technological advantage and reduction in software costs."

About LISI AEROSPACE

LISI AEROSPACE, part of LISI GROUP, is one of the leading providers of aeronautical fasteners and assembly components and ranks third in the world. LISI AEROSPACE has more than 2,900 employees and 10 factories throughout North America and Europe.

LISI AEROSPACE's major clients include AIRBUS, BOEING, EMBRAER, BOMBARDIER, DASSAULT, GEAE, PRATT & WHITNEY, ROLLS ROYCE, SAFRAN, EUROCOPTER and all worldwide equipment manufacturers in the aeronautics sector.

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Product News

ANSYS Releases ANSYS Icepak 12.0 Software

1 July 2009

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ANSYS, Inc. announced the latest release of ANSYS® Icepak® software, which provides powerful fluid dynamics technology for electronics thermal management. The 12.0 release introduces new solutions for printed circuit board (PCB) and package thermal analysis, new and enhanced technology for meshing complex geometry, and new physical modeling capabilities. These advances enable engineers who design electronic components for products such as cell phones, computers and graphics cards to improve design performance, reduce the need for physical prototypes and shorten time to market in the highly competitive electronics industry.

ANSYS Icepak software accelerates the product development process by accurately simulating the dissipation of thermal energy in electronic devices at the component, board or system level. Based on the state-of-the-art ANSYS® FLUENT® CFD solver, ANSYS Icepak software has a streamlined user interface that speaks the language of electronics design engineers, enabling the rapid creation of models of complex electronic assemblies. Integration of ANSYS® Iceboard® and ANSYS® Icechip® capabilities into ANSYS Icepak 12.0 provides engineers with an integrated platform to analyze package, PCB and system designs. Direct import of electronic CAD (ECAD) designs allows engineers to model all components of packages and PCBs, including, traces, vias, solder balls, solder bumps, wire bonds and dies. A new PCB trace Joule heating modeling capability along with the import of DC power distribution profiles from Ansoft SIwave™ software significantly enhance the accurate thermal simulation of PCBs. ANSYS Icepak 12.0 also offers enhanced fan modeling capabilities, parallel processing, post-processing, and new libraries including heat sinks, thermo-electric coolers, materials and enhanced macros. In keeping with the ANSYS comprehensive multiphysics strategy, ANSYS Icepak technology used in conjunction with SIwave and ANSYS® Mechanical™ products provides a coupled solution to meet the electrical, thermal and structural requirements of the electronics design engineer.

“ANSYS Icepak 12.0 addresses the thermal management simulation challenges facing engineers designing electronic components. With today’s high-performance electronic devices, there is a trend to reduce device size while increasing product functionality. This trend increases power densities in devices, which necessitates that thermal management become a design driver,” said Dipankar Choudhury, vice president of corporate product strategy and planning at ANSYS, Inc.

ANSYS Icepak 12.0 brings greater automation and flexibility for meshing complex electronics geometry. Two new meshing technologies — automatic multi-level meshing and Cartesian hex-dominant meshing — significantly enhance the software’s ability to handle complex geometries and improve accuracy without sacrificing robustness. New meshing enhancements provide improved mesh smoothness, quality, curvature and proximity capturing, and speed. The automatic generation of highly accurate, conformal meshes that represent the true shape of electronic components and the solution of fluid flow and all modes of heat transfer — conduction, convection and radiation — for both steady-state and transient thermal flow simulations enable engineers to rapidly evaluate thermal management issues for electronic devices, with a reduction in development time and increased product reliability as a result.

[ANSYS](#) Icepak 12.0 adds depth and breadth to the individual physics and modeling technologies that are part of the complete ANSYS multiphysics portfolio, which also includes Ansoft electromagnetic, electromechanical, circuit and system behavior technologies.

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Cadence Collaborates with Toshiba Corporation on Integrated Design Environment for COT and

SoC Design

29 June 2009

Cadence Design Systems, Inc. announced an extensive collaboration with Toshiba Corporation Semiconductor Company to address the challenges of existing and next-generation SoC designs. Toshiba is a leading provider of process and design solution for cutting-edge SoC products. Based on the [Cadence® Encounter® Digital Implementation System](#) and the [Cadence Virtuoso® Custom Design Solution](#), the collaboration provides a full digital and mixed-signal design environment to Toshiba and its COT customers for the most advanced semiconductor products where integration of digital and mixed-signal designs is a key to success.

“In highly competitive markets such as wireless and consumer devices designers are expressing a growing requirement for integration of digital and mixed-signal content on ever-smaller semiconductor devices,” said Tatsuo Noguchi, Technology Executive for SoC of Toshiba Corporation Semiconductor Company. “Because the Cadence Encounter and Virtuoso design environments provide the industry-leading analog and digital design flows necessary to meet these challenges, we are delighted to work closely with Cadence and help our COT customers realize their highly integrated custom IC design. We expect the collaboration to continue to provide benefits to the design community going forward.”

The ongoing collaboration focuses primarily on physical implementation, verification, and custom analog integration for COT and SoC designs. The physical implementation flow includes Cadence Encounter RTL Compiler, Cadence Conformal® verification suite, Cadence QRC Extraction and the Encounter Digital Implementation System. The Toshiba flow utilizes Cadence Encounter Timing System for timing verification, Cadence Physical Verification System for physical verification, Cadence Virtuoso IC 6.1 for custom analog design and Cadence process design kits (PDKs) for quicker, more accurate design.

“Cadence has worked extensively over the years with Toshiba Semiconductor to provide the design environment necessary to meet all the latest challenges to COT and SoC designs,” said Chi-Ping Hsu, senior vice president of the Implementation Products Group at Cadence. “We’re confident that this association will continue to deliver the design flows necessary to create high-quality semiconductor products.”

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Collision Avoidance in 3D Immersion

29 June 2009

TechViz and Kineo CAM present the optimal software solution of accessibility research for mounting and dismounting of complex systems both in **immersive AND assisted** mode. Its aim is to be able to analyze the mounting or dismounting of complex systems by immersing the end-user while bringing him with a series of assistance functionalities.

Can the power generator be mounted in (dismounted from) the engines room?

Until now, to answer this question during 3D design, there were two types of solutions: the first one based on software on desktop and the second one based on virtual reality environment. The most advanced solutions of the first type are able to propose automatic search capabilities for collision-free trajectory; Those of the second type are based on interactive systems of tracking. The first ones enable to quickly and easily find solutions and give little credit to the operator; The second ones on the contrary put the operator

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in the heart of the mockup and then often in the heart of difficulties with very little assistance.

TechViz and Kineo CAM propose to put the operator in the heart of its 3D mockup and to be able to interact with it being assisted in order to ease the search and validation of mounting or dismounting trajectories.

Virtual reality solutions are very much oriented on the free navigation within the mockup but they too often lack analysis helping tools during operator's interactions – mockup : collision detection while in movement, analysis of obstacles distances in real time and even better, assistance to collision avoidance along the trajectory.

The technical solution proposed by the partners implement products already tested separately within the automotive and nuclear industries; indeed this is the offer TechViz XL associated to Kineo:

TechViz XL enables to display an existing 3D application on a frame wall, in stereo mode with tracking, to offer a complete collaborative work environment on immersive mode.

Kineo Path Planner enables to manage collisions in 3D environment with its highly performing collision detector KCD™ and to automatically search collision-free trajectories.

In order to visualize a demonstration video, visit www.kineocam.com/news-events.php

About TechViz

[TechViz](#) offers the only solution on the market enabling to work on existing 3D applications for visualization systems in immersive, collaborative and network mode.

TechViz combines the power of last generation 3D graphic cards and a specific software to offer display systems and graphics with unmatched performances and functionalities. TechViz products lead the way to new functionalities of your existing applications.

Based in Paris – France, TechViz customers come from various markets: public labs, military research programs, energy or manufacturing industries, and other visualization technologies users. For more information: www.techviz.net

About Kineo CAM

[Kineo Computer Aided Motion](#) “Kineo CAM” is the independent software developer of the global technology for automatic motion and path planning, KineoWorks™.

Specialized in the development of advanced solutions, Kineo CAM provides business solutions to large companies and organizations in the United States, Europe and Japan.

The main market of Kineo CAM is Mechanical Computer-Aided Design and Manufacturing. In this area, the large range of solutions, from stand-alone to fully integrated software, enables users to save money, shorten development time and increase quality in Product Design (validation of mechanical mounting/dismounting) and Process (simulation of operations in cluttered 3D environments).

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Interoperability a Key Enhancement of AVEVA Marine

2 July 2009

AVEVA announced that it has made further enhancements to its AVEVA Marine portfolio.

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With a main focus on interoperability, this new release of the AVEVA Marine portfolio now offers AVEVA's marine customers extended possibilities for data exchange between various sources.

AVEVA Marine users will now be able to integrate P&IDs and schematic diagrams coming from various systems, including the AVEVA P&ID solution.

This brings a real benefit to customers as they are now free to select their P&ID system from various sources and even to integrate P&IDs from other authoring systems into a complete model of their project.

AVEVA Marine now also offers a completely new Mechanical Equipment Interface product using the Step AP203 format. This allows AVEVA Marine users to import mechanical equipments from various sources - generally generic or mechanical CAD systems - and utilize them in the model as any Outfitting component. Equipment models, like main engines, compressors or pumps can now be directly supplied by the manufacturer and placed with great accuracy in the 3D model, thus reducing the risk of errors.

Finally, more interoperability between Plant and Marine Outfitting can be achieved as data in both databases is now made fully exchangeable. This will allow customers using AVEVA's solutions both in the plant and the marine sectors to share their models in a much easier way. As an example, FPSO designers and builders will now be able to share the same data model for the Outfitting part of the vessel and the top-side. This leads to reduced design time and better consistency between top-side and floating platform design.

Bruce Douglas, Vice President of Marketing and Product Strategy at AVEVA said:

"AVEVA Marine is an integrated solution for shipbuilders, ship designers and ship operators. It allows engineers and designers on multiple sites to concurrently create, control and manage change to engineering, design and production data as a project is developed, in the most productive and risk-free way."

Richard Longdon, CEO of AVEVA said:

"Earlier this year, we announced the introduction of AVEVA Instrumentation and AVEVA Diagrams to the plant and marine portfolios. These products, plus the latest enhancements, have further strengthened the AVEVA Integrated Design and Engineering offer both to our ship operators and shipyards clients.

"For ship operators we have an Operations Information Integrity solution that delivers real cost savings. And for ship builders and ship design agents, our Integrated Project Execution solution saves time and money during the project."

For more information on AVEVA Marine see the website at <http://www.aveva.com/marine>



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LightWork Design Releases LightWorks 8.1

1 July 2009

LightWork Design announced the release of LightWorks 8.1 which provides LightWorks customers with yet more enhanced rendering functionalities.

The main focus of this release is the development of the LightWorks Real-time rendering product, alongside some improvements to EPix output. These include:

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- Soft shadows and Shadow catching are now both supported by Real-time rendering, using programmable shading;
- Programmable shading is now supported for several more LightWorks material shaders, for example multilayer paints and leathers, and this gives real-time support which is closer to the software implementation;
- EPix output can now be anti-aliased giving users more defined and accurate rendering.

David Forrester, Managing Director at LightWorks commented: "We appreciate that globally, many companies are experiencing difficult economic times at the moment and we want to help our customers to increase the value of their products. The release of LightWorks 8.1 comes quickly after the release of LightWorks 8.0 as we have accelerated our development plans to bring new functionality to our customers even more quickly."

LightWorks customers are already seeing the benefits of these product advancements: Roland Roeder, PTC GmbH commented: "The real-time shadow catcher support in 8.1 is great news for us and the leather shaders work really well! We're also finding that the added support for real-time soft shadows is making a big difference when we use LightWorks real-time rendering."

LightWork Design

LightWork Design is a leading supplier of rendering solutions for developers of advanced 3D computer graphics software. Renowned for its physically accurate visualisation of real-world objects and environments, LightWorks is the ideal choice for applications targeted at the AEC, Configuration, and Industrial markets. LightWorks is supplied as a complete solution which includes the SDK, support, training and consultancy services, to give customers fast and efficient access to leading-edge rendering technology, resulting in shorter development cycles, faster time-to-market for new products, and lower software development costs.

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Mentor Graphics Extends Catapult C w/Support for Control Logic to Enable Full-Chip High-Level Synthesis

29 June 2009

Mentor Graphics Corp. announced that the Catapult® C Synthesis tool has been extended to support control logic and manage low power design requirements, thus enabling full-chip high-level synthesis (HLS). This breakthrough technology allows designers to use pure ANSI C++ for both algorithmic blocks and control logic blocks. Extending the Catapult C tool's capabilities to full-chip high-level synthesis is critical due to the rapid growth in design size and complexity, which requires engineers to design hardware functionality at higher levels of abstraction.

Control logic synthesis and algorithmic synthesis have traditionally been addressed using different languages, formalisms and abstractions. The latest advances in the Catapult C Synthesis tool unifies these two domains, allowing users to describe control logic along with algorithmic behavior in a single and coherent model leveraging standard ANSI C++.

At the heart of this innovation is a new synthesizable C++ construct, which allows designers to easily specify asynchronous data communication, allowing full control over concurrent hardware creation. This pivotal mechanism allows interfacing algorithmic representations driven by the dataflow with

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control-dominated blocks synchronized by clocks. The result is a coding style familiar to hardware designers, letting users easily express communication, priority and task coordination within an abstract representation of concurrency. The new approach formalizes a modeling style, which provides the necessary accuracy for control oriented tasks, while preserving the abstraction beneficial for algorithmic subsystems.

The synthesis process is complemented by a patent-pending and fully automated verification flow which for the first time lets users validate the detailed RTL-level block interactions at the C level. Tight integration between verification and synthesis has proved a necessity to realizing the full potential of HLS. A common pitfall found with other HLS tools is developing high-level synthesis in isolation, which results in overly complex verification of the RTL output.

"Our digital broadcasting ICs typically consist of a complex mix of compute intensive algorithmic units and control dominated blocks," said Professor Schlicht, Head of Department, Fraunhofer Institute for Integrated Circuits. "The new Catapult extensions for control-logic synthesis provide us with the capability to develop an increasing portion of the overall system using high-level synthesis from C++. This allows us to extend our C++ based implementation flow beyond the pure signal processing blocks."

In addition to support for control logic, the Catapult C Synthesis tool has added innovative technology for low power design by automating two prevailing design techniques: multi-level clock gating and interfacing to dynamic power and clock management units. The Catapult C tool will analyze deep cones of logic to find gateable clocks, an otherwise error-prone and manual task typically done by backend low power experts. This new and unique optimization delivers near 100% perfect clock gating by operating at the flop level, maximizing power savings by locally inferring the gating logic surrounding the targeted registers. To help further reduce power, the Catapult C Synthesis tool also exports real-time information on the state of all system blocks. This information is relayed to power management units leveraging dynamic frequency and voltage scaling heuristics to achieve system-wide power savings. As expected, dynamic power savings is design and test vector dependent; measurements on more than 300 customer designs showed improvements ranging from 10 to 90%, with an average improvement of 40%.

"The control logic extensions of Catapult C now let us develop a larger part of our systems with HLS," said Emmanuel Liegeon, Deputy Manager of Digital ASIC & FPGA Design Group, Thales Alenia Space. "As we develop more and more of the system in HLS, it becomes paramount to get power right. The latest enhancements in Catapult C for low power are delivering the optimizations we need."

About Catapult

The Catapult C Synthesis tool is the first product to automatically generate control and algorithmic RTL multi-block designs from a pure ANSI C++ source where both the core algorithm and interface are untimed. This productivity improvement gives designers time and freedom to automatically perform detailed design exploration of different micro-architectural options and interface scenarios to quickly achieve fully optimized hardware designs.

Product Availability

The Catapult C Synthesis 2009a release is available to customers in July. The Catapult C product family ranges from \$140,000 to \$390,000. For more product information on the Catapult C tool, contact your Mentor Graphics sales representative, call 1-800-547-3000, or visit the website at

<http://www.mentor.com/products/esl/catapult-c>



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OptiTex Introduces Fabric Testing Utility

1 July 2009

OptiTex is about to release its Fabric Testing Utility (FTU). The FTU was designed to further advance the OptiTex system's ability to recreate the dynamics of fabric movement on fully adjustable, lifelike virtual mannequins.

“Our new FTU is a remarkable tool in that it not only enhances our industry-leading technology, it also saves our customers thousands of dollars in the long run,” states Ran Machtinger, President and CEO of OptiTex, Ltd. “Now, OptiTex users can test fabrics in house rather than use a costly, time-consuming external service.”

OptiTex's FTU is a lightweight, briefcase-sized device that accurately measures the four principal types of fabric strain: Bend, stretch, shear and friction. The machine has an automated repeat function to validate the measurements. As with all OptiTex products, the FTU was designed to provide the user-friendly experience that OptiTex customers have come to expect.

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